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International Bureau



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁷ : H01L 21/316	A1	(11) International Publication Number: WO 00/51174 (43) International Publication Date: 31 August 2000 (31.08.00)
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(21) International Application Number: PCT/GB00/00671

(22) International Filing Date: 24 February 2000 (24.02.00)

(30) Priority Data:

9904427.3	26 February 1999 (26.02.99)	GB
9922801.7	28 September 1999 (28.09.99)	GB
0000780.7	14 January 2000 (14.01.00)	GB

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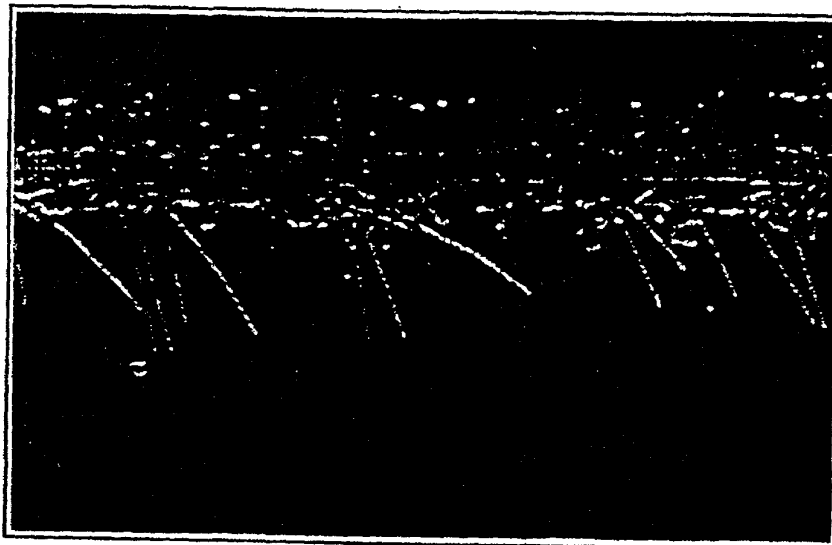
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(81) Designated States: AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CR, CU, CZ, DE, DK, DM, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, US, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, TZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published

With international search report.

(54) Title: A METHOD OF PROCESSING A POLYMER LAYER



← Wafer edge

Edge cracking as seen by optical microscope under dark field illumination

(57) Abstract

This invention relates to a method of processing polymer layers, for example low dielectric constant films, and includes the steps of heating the layer to desorb moisture and harden the layer and exposing the layer to a plasma during the heating process.